TOSHIBA FAST RECOVERY DIODE SILICON DIFFUSED TYPE

100FXFG13, 100FXFH13

HIGH SPEED RECTIFIER APPLICATIONS

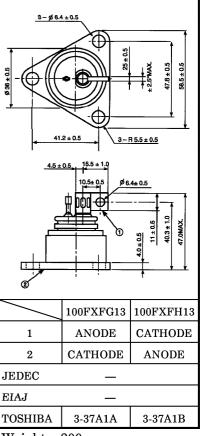
Unit in mm

Repetitive Peak Reverse Voltage : $V_{RRM} = 3300V$ Average Forward Current $: I_{F(AV)} = 100A$

Reverse Recovery Time ($T_j = 25$ °C) : $t_{rr} = 3.1 \mu s$

MAXIMUM RATINGS

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Repetitive Peak Reverse Voltage	v_{RRM}	3300	V	
Non-Repetitive Peak Reverse Voltage (Non-Repetitive ≤ 5 ms, $T_j = 0 \sim 125$ °C)	V _{RSM}	3400	V	
Average Forward Current	I _{F (AV)}	100	A	
Peak One Cycle Surge Forward	Incre	2000 (50Hz)	A	
Current (Non-Repetitive)	IFSM	2200 (60Hz)		
Junction Temperature Range	T_{j}	-40~125	$^{\circ}\mathrm{C}$	
Storage Temperature Range	$T_{ m stg}$	-40~125	$^{\circ}\mathrm{C}$	
Screw Torque	_	1.6	N∙m	



Weight: 200g

ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITION		MIN.	MAX.	UNIT		
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM} = 3300V, T_j = 125^{\circ}C$		_	30	mA		
Peak Forward Voltage	$ m v_{FM}$	$I_{FM} = 320A, T_j = 25^{\circ}C$		_	2.2	V		
Reverse Recovery Time		$I_{\mathbf{F}} = 100 A$	$T_j = 25$ °C		3.1	449		
		$di_{\mathbf{F}}/dt = 100 \mathrm{A}/\mu \mathrm{s}$	$T_j = 125$ °C	_	4.0	μ s		
Thermal Resistance	$ m R_{th~(j-c)}$	Junction to Fin		_	0.18	°C/W		

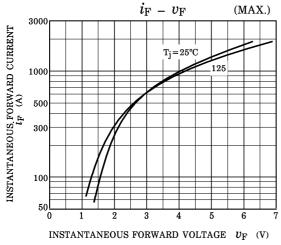
Note: Contact thermal resistance R_{th (c-f)}=0.04°C/W (Applied silicone grease)

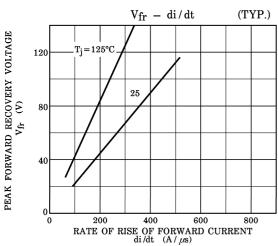
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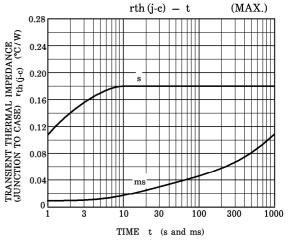
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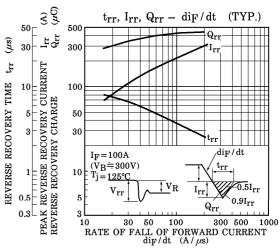
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